



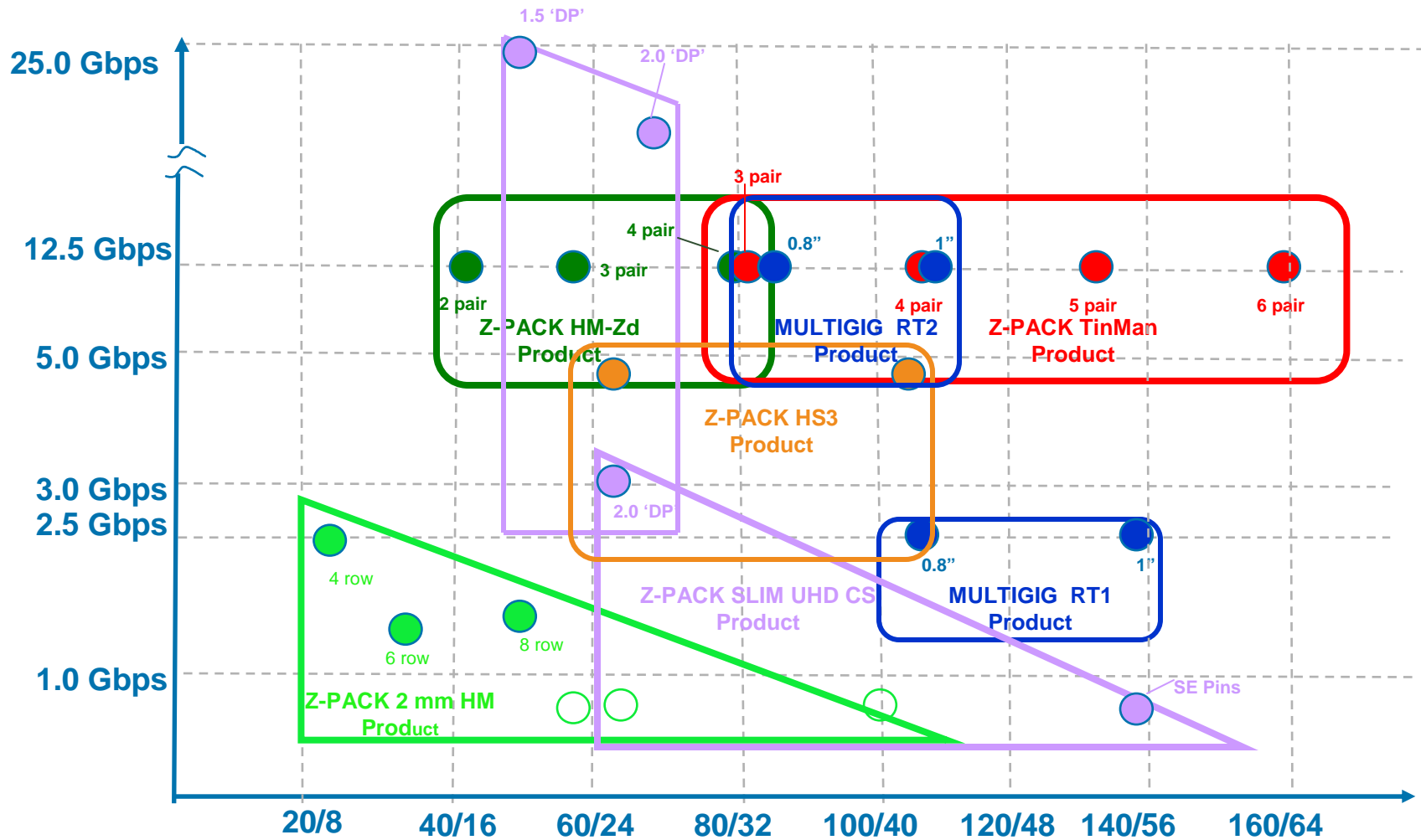
Z-PACK TinMan Connector System

May 13, 2011

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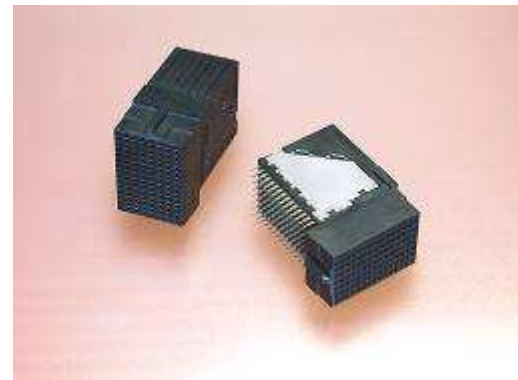
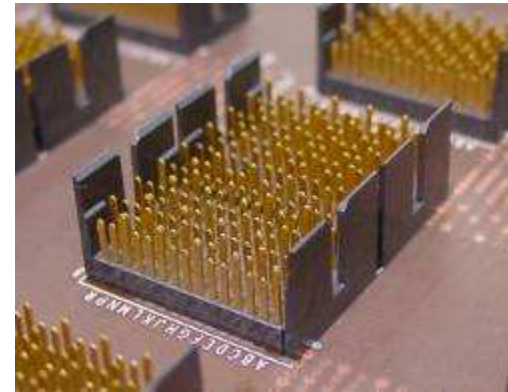


Backplane Connectors Roadmap



Z-PACK TinMan Connector System

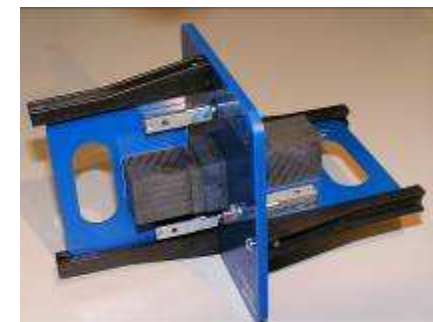
- Exceptional differential performance, 12+ Gb/s
- High density
- Low cost
- Bellcore/Telcordia compliant
- Repairable pins on backplane
- Fully compliant with all “HM” compliant guide and power modules



Telcordia is a trademark of Telcordia Technologies, Inc.

Z-PACK TinMan Connector System Connector Configurations

- Traditional backplane configuration
 - Vertical header to R/A receptacle
- Co-planar applications
 - R/A header to R/A receptacle
- Mezzanine applications
 - Vertical header to vertical receptacle
- Midplane cross-connect (“orthogonal”) applications

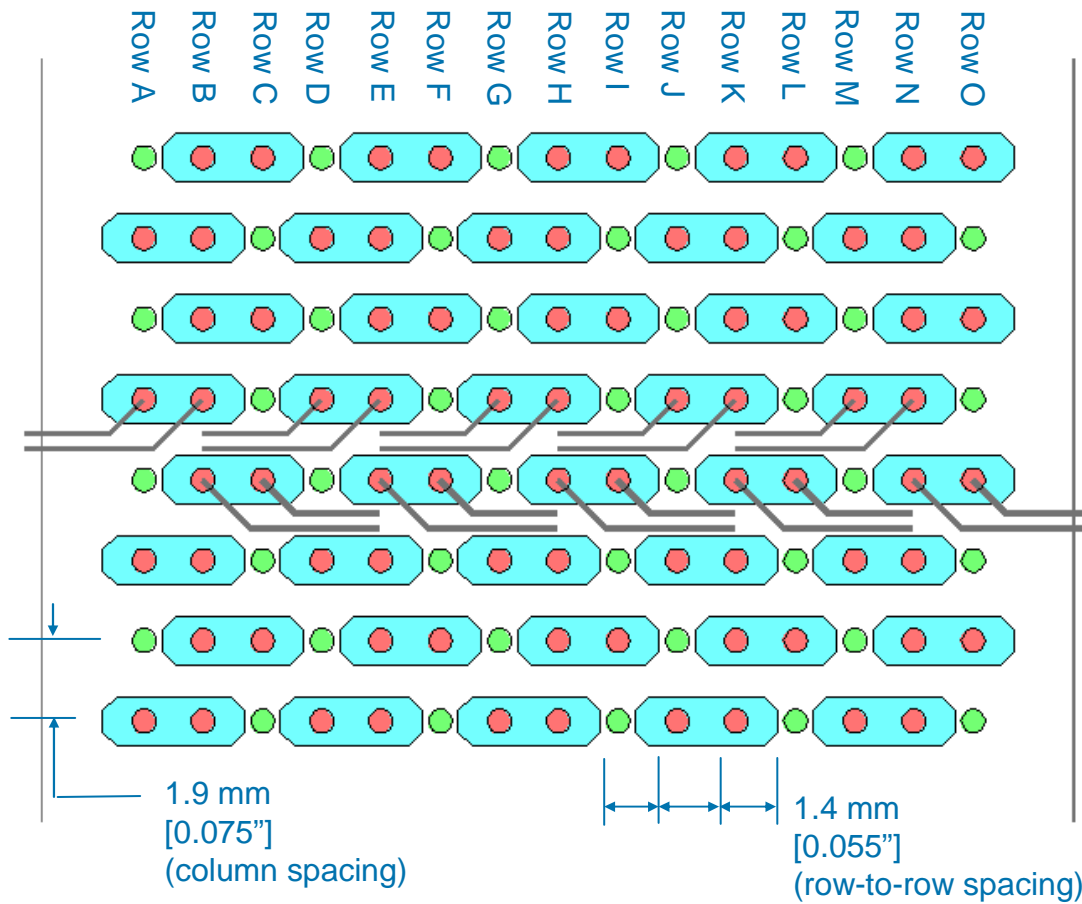


Z-PACK TinMan Connector System Density Options

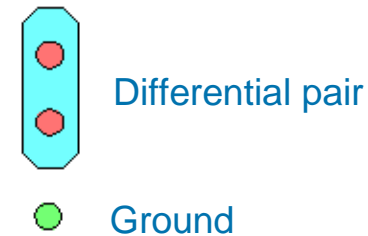
Pairs per Column	Part Envelope mm [in]	Density Pairs/cm [Pairs/in]	Column Pitch mm [in]
3 Pair	16.0 mm [0.630"]	15 /cm [40 /in]	1.9 mm [0.075"]
4 Pair	20.2 mm [0.795"]	21 /cm [53 /in]	1.9 mm [0.075"]
5 Pair	24.4 mm [0.961"]	26 /cm [66 /in]	1.9 mm [0.075"]
6 Pair	28.6 mm [1.126"]	31/cm [80 /in]	1.9 mm [0.075"]

- Parts available with and without end walls
- All parts 12+ Gbps capable

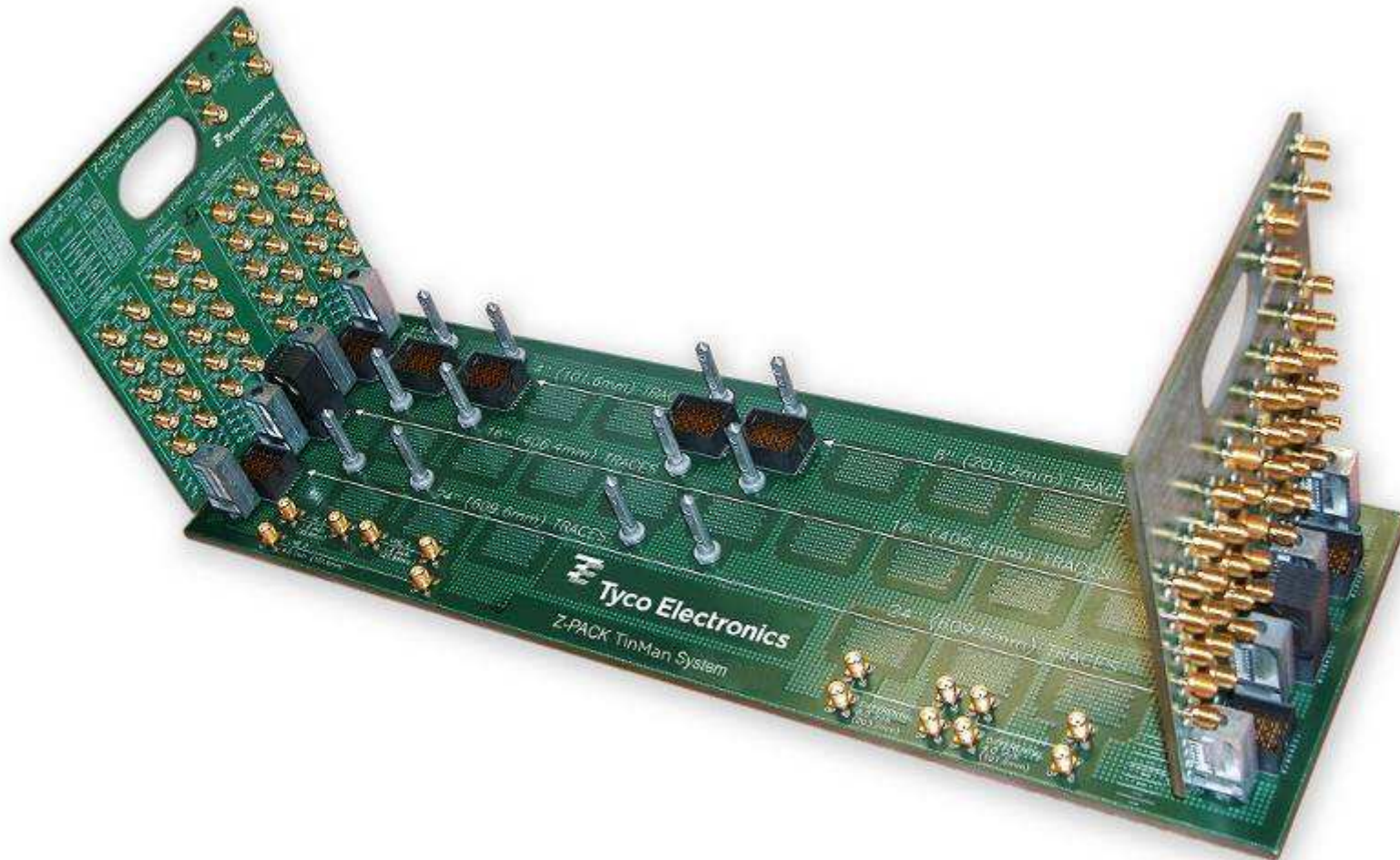
Z-PACK TinMan Connector System Footprint Via Pattern



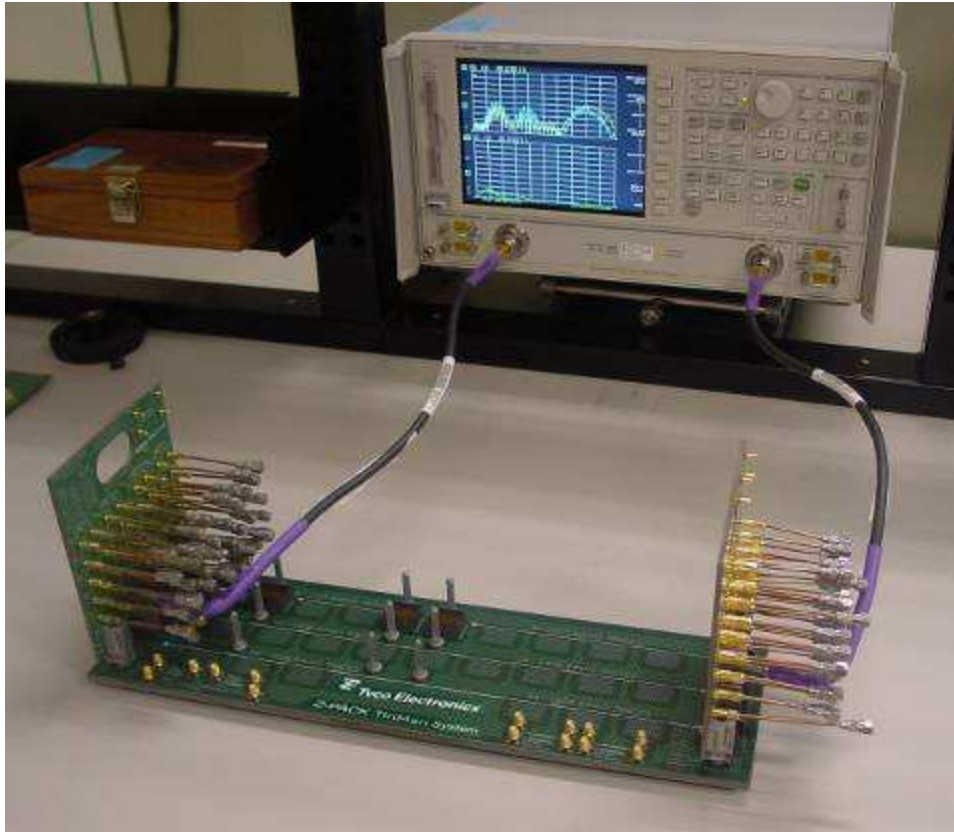
- Supports 0.2 mm [0.008"] traces
- Flipped columns reduce via-to-via noise
- 0.46 mm [0.018"] finished diameter via
- Straight route out
- 5 layer breakout (5-pair)
- Same BP & DC footprint
- Routing guide available
- Allegro parts available for some configurations



Z-PACK TinMan Connector System System Evaluation Kit



Z-PACK TinMan Connector System System Evaluation Kit

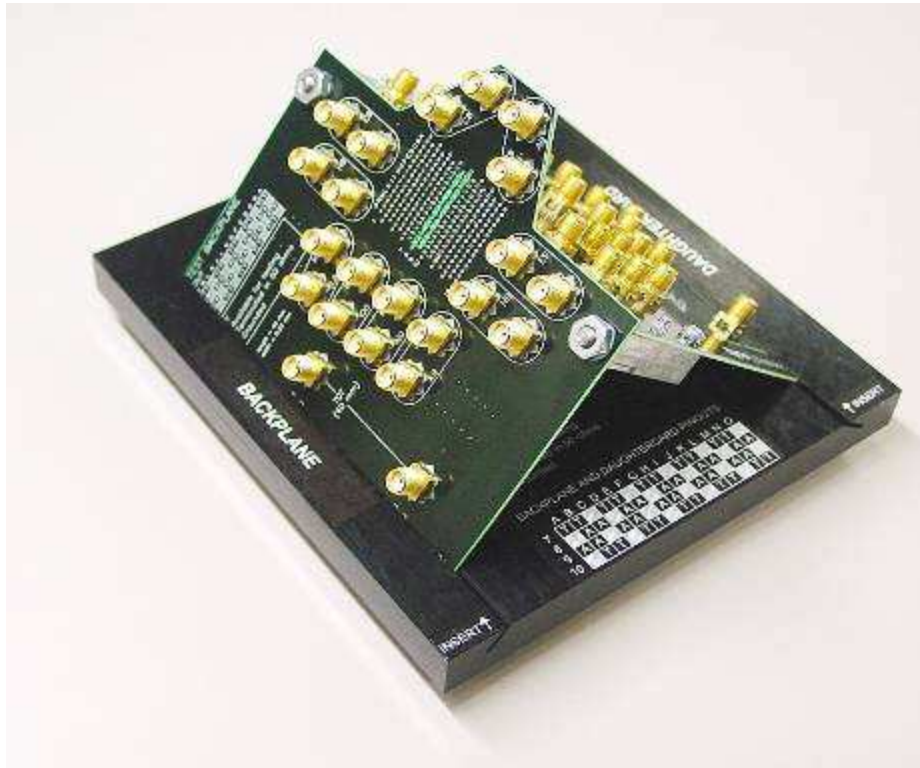


- Provides data showing the connector's performance in a typical system environment
- 2 Daughtercards
 - 3.18 mm [0.125"] thickness
 - Nelco 4000-6 material
 - 127 mm [5.0"] trace length
 - 0.13 mm [0.005"] trace width
- Backplane
 - 5.08 mm [0.200"] thickness
 - Nelco 4000-13 material
 - Various trace lengths
 - 0.18 mm [0.007"] trace width
- Links with and without counterboring
- Available for loan

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Z-PACK TinMan Connector System

Connector-Only Evaluation Kit



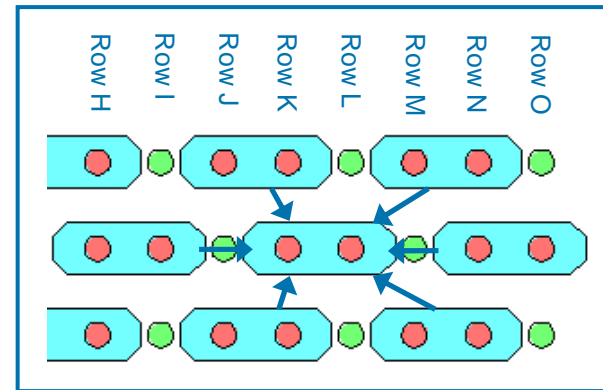
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- Same test boards used for all tests
- Provide “connector only” data (minimal footprint)
- 1.5 mm [0.060”] board thickness
- Bottom layer via connect
- Short traces (40 mm [1.575”])
- Available for loan
- Following data tested using
 - TDS8000 Digital Sampling Oscilloscope
 - Agilent E8364B PNA Analyzer

Z-PACK TinMan Connector System

Worst-case NEXT/FEXT, Worst-case Pinout

Pair	NEXT	FEXT
AB9	1.1%	0.5%
BC8	2.5%	1.0%
DE9	2.9%	1.1%
EF8	2.7%	1.1%
GH9	2.7%	1.1%
HI8	2.8%	1.2%
JK9	2.7%	1.0%
KL8	2.6%	1.1%
MN9	2.1%	0.9%
NO8	0.9%	0.5%

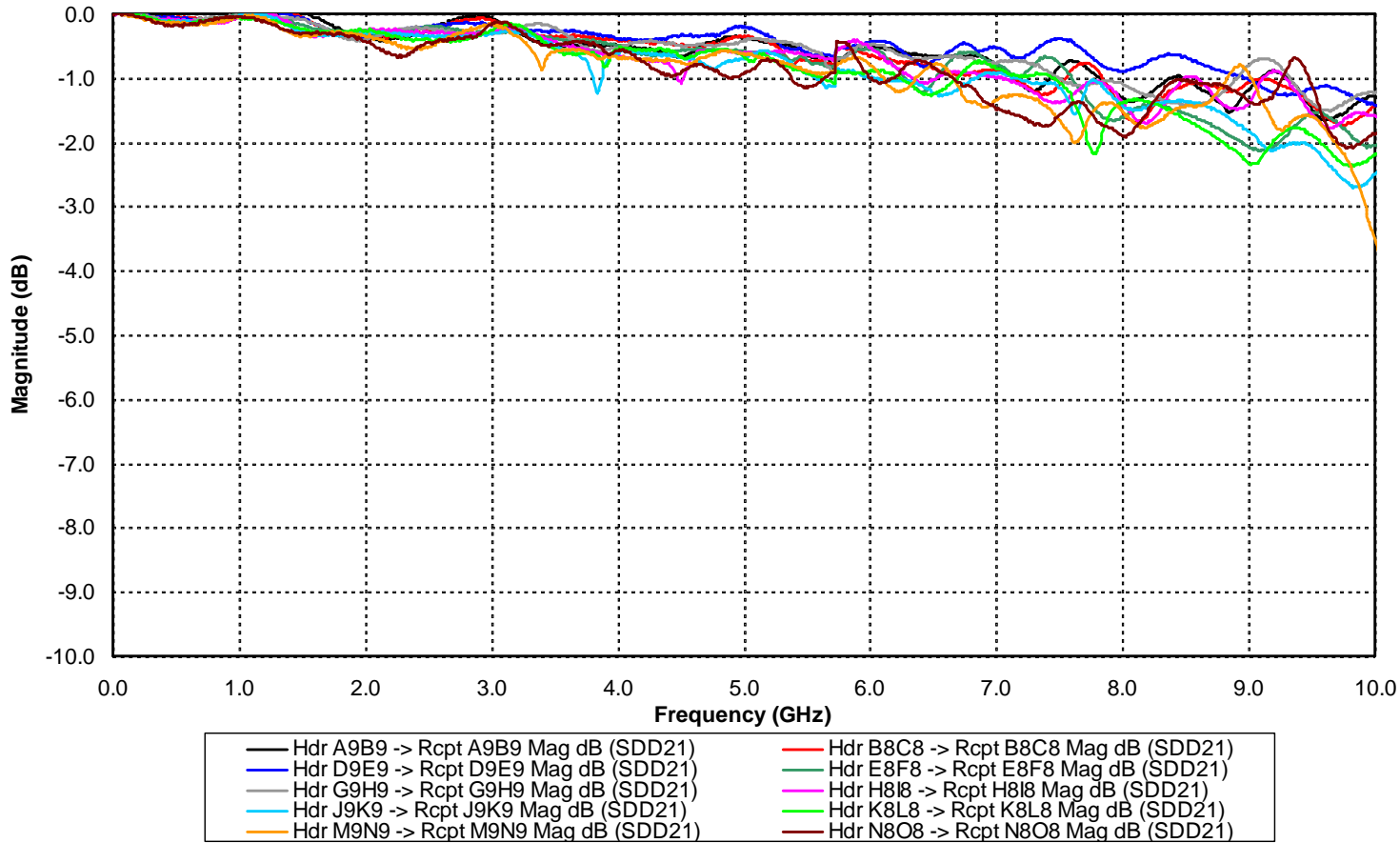


- TEST DATA
- Single mated 5-pair 1.9 mm column pitch connector
- Vertical header
- R/A receptacle
- 50 ps (20-80%) edge rate
- Vertical header driven far end crosstalk
- Includes two 1.5 mm [0.060"] vias to bottom layer traces
- Asynchronous sum of peaks from each aggressor
- Percentage is total noise divided by differential swing (A-B)

Z-PACK TinMan Connector System

Differential Insertion Loss

Z-PACK TinMan 5pr 1.9mm VHdrR1-RARcptR4



- TEST DATA
- Single mated 5-pair 1.9 mm column pitch connector
- Vertical header
- R/A receptacle
- Includes two 1.5 mm [0.060"] vias to bottom layer traces

THANK YOU